

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<p>In re Patent Application: Rajeev Joshi et al.</p> <p>Serial No.: 10/731,453</p> <p>Filed: December 9, 2003</p> <p>For: WAFER-LEVEL CHIP SCALE PACKAGE AND METHOD FOR FABRICATING AND USING THE SAME</p>	<p>Confirmation No. 4432</p> <p>Group Art Unit: 2891</p> <p>Office: Zarnecke, David A.</p>
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Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

REQUEST FOR RECONSIDERATION

In response to the Office Action mailed on August 20, 2007, Applicants respectfully request reconsideration of this application in light of the following remarks.

Remarks begin on page 2 of this paper.